TITLE: Heat Dissipation in Semiconductor Assemblies

ABSTRACT

A method of constructing a semiconductor assembly, a semiconductor assembly, and a structure for use in the construction of a semiconductor assembly are disclosed. The method is characterised by the use of a thermally conductive frame (8) that is positioned to define a mould wall for retaining an encapsulent material (9). In the manufactured semiconductor assembly the thermal conductive frame (8) dissipates heat that is generated in use of the semiconductor assembly. The structure comprises a support framework (19) for one or more of the thermally conductive frames (8) and a plurality of tie-bars (13, 14, 15, 16) which connect the frames (8) and the framework (19).

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